

POLISHING APPARATUS AND METHOD OF BONDING AND REMOVING  
EXPENDABLE REPLACEMENT COMPONENTS THEREOF

ABSTRACT OF THE DISCLOSURE

A polishing apparatus includes a top ring for holding  
5 a substrate and a polishing table having a polishing  
surface. The substrate held by the top ring is brought  
into contact with the polishing surface, and in this state,  
the polishing table and the substrate are moved relative to  
each other to thereby polish the substrate. Expendable  
10 replacement components to be bonded to the top ring and the  
polishing table, such as a backing film, a pressure ring  
and a polishing cloth, are bonded in such a manner that  
pieces of heat-sensitive adhesive tape are interposed  
between the expendable replacement components on the one  
15 hand and the top ring and the polishing table on the other.  
The heat-sensitive adhesive tape is switchable between a  
non-adhesive state and a adhesive state according to  
whether the temperature thereof is higher or lower than a  
predetermined set temperature. Thus, the expendable  
20 replacement components can be bonded and removed extremely  
easily by the temperature control of the heat-sensitive  
adhesive tape.